

AgilLink™ 1.20mm Wire-to-Board Header G823H

CUSTOMIZABLE SHROUDED WIRE-TO-BOARD HEADER

AgilLink™ 1.20mm wire-to-board header G823H series is the most common solution for transferring power and signal. This series can carry a maximum current rating of 1A. Amphenol ICC offers a comprehensive range of these headers including vertical and right angle SMT to meet various customer requirements. It is offered in customizable high current ratings, which makes it an ideal choice for several applications and specific designs.

- Saves space with 1.20mm pitch
- Snap-in mating
- Lock option
- Supports PiP process
- Easy pin insertion and high retention force onto PCB



TARGET MARKETS



FEATURES

- Low profile design
- Available in both vertical and right angle SMT
- High temperature thermoplastic material
- Tape and reel packaging option
- RoHS compliant and halogen-free
- Snap-in mating design
- Mates with G823H and G823F/C wire-to-board headers

BENEFITS

- Saves device space
- Ease in choosing board mating configurations
- Reflow compatible
- Supports PiP process
- Meets environmental, health and safety requirements
- Easy mating and unmating
- Mutually compatible with other wire-to-board connectors

TECHNICAL INFORMATION

MATERIAL

- Housing: High temperature thermoplastic, UL94V-0
- Contact: Copper alloy, selective gold or tin plating on contact area, gold flash or tin plating on solder tail and nickel under-plated overall

MECHANICAL PERFORMANCE

- Contact Retention Force: Base on individual P/N
- Durability: 30 cycles
- Insertion Force: Base on individual P/N
- Withdrawal Force: Base on individual P/N
- Vibration: 1µs max., EIA 364-28
- Mechanical Shock: 1µs max., EIA 364-27

ELECTRICAL PERFORMANCE

- Current Rating: 1A AC/DC
- Voltage Rating: 50V AC/DC
- Temperature: -40°C to +85°C
- Contact Resistance: 20mΩ max.
- Insulation Resistance: 100MΩ min.

PACKAGING

- Tape and reel
- Bag

SPECIFICATION

- Amphenol Product Specification: GS-823H

ENVIRONMENTAL

- Thermal shock:
 - a) -55°C to 30 minute
 - b) +85°C to 30 minute, 10 cycles, EIA 364-32
- Humidity: 60°C, 90 to 95%RH, 240 hours, EIA 364-31
- Heat Resistance : 85°C, 96 hours, EIA 364-17
- Cold Resistance: -40°C, 96 hours, EIA 364-17
- Solder-ability: 95% min. solder coverage, EIA 364-52
- Resistance to Soldering Heat: Peak temperature: 260°C max., 10 seconds max.

APPROVALS AND CERTIFICATION

- USCAR-2 compliant
- RoHS compliant
- Reach/SVHC compliant

TARGET MARKETS/APPLICATIONS



Communications



Consumer



Server
Storage



Industrial & Instrumentation



Medical